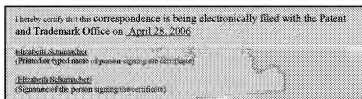


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Nagesh R. Basavanhally, *et al.*  
Serial No.: 10/816,527  
Filed: March 1, 2004  
Title: HIGH DENSITY NANOSTRUCTURED INTERCONNECTION  
Grp./A.U.: 2822  
Examiner: Kiesha L. Rose

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450



Sir:

**AMENDMENT UNDER 37 C.F.R. § 1.116**

In response to the Examiner's Action mailed March 27, 2006, please amend the above-identified application as follows: